

**MOSER, PATTERSON & SHERIDAN, L.L.P.**

Attorneys at Law  
3040 Post Oak Boulevard, Suite 1500  
Houston, Texas 77056-6582  
Telephone (713) 623-4844  
Facsimile (713) 623-4846  
[www.mpsllp.com](http://www.mpsllp.com)

**FACSIMILE COVER SHEET**

<b>DATE:</b>	January 3, 2003	<b>FILE NO:</b>	AMAT/4471.Y1/CPI/COPPER/PJS	
<b>TO:</b>	Examiner E. SMITH-HICKS		<b>FAX NO:</b>	703/872-9746
<b>COMPANY:</b>	UNITED STATES PATENT AND TRADEMARK OFFICE			
<b>FROM:</b>	ARI O. PRAMUDJI		<b>PAGE(S):</b> with cover	4
<b>MESSAGE:</b>			<b>Original to Follow</b>	NO

**OFFICIAL FAX****PROPOSED AMENDMENT**

U.S. Serial No.: 09/614,407  
Confirmation No.: 1903  
Filing Date: July 12, 2000  
Inventors: Zheng, et al.  
Examiner: E. Smith-Hicks  
Group Art Unit: 1741

T:\CLIENTS\IAPPM4000-4889\4471.Y1\PTOFAX - PROPOSED A.MDNDMNT.DOC

**CONFIDENTIALITY NOTE**

The document accompanying this facsimile transmission contains information from the law firm of Moser, Patterson & Sheridan, L.L.P. which is confidential or privileged. The information is intended to be for the use of the individual or entity named on this transmission sheet. If you are not the intended recipient, be aware that any disclosure, copying, distribution or use of the contents of this fixed information is prohibited. If you have received this facsimile in error, please notify us by telephone immediately so that we can arrange for the retrieval of the original documents at no cost to you.

**PROPOSED AMENDMENTS**  
**FOR 09/614,407**

Spec support  
cited as  
shown.

Please amend the claims as follows:

85. (Amended) A method of depositing a metal on a substrate having one or more features formed thereon, comprising:

applying a first biasing voltage to the substrate while immersing the substrate into an electrolyte solution contained in an electrolyte container comprising an anode immersed in the electrolyte solution, wherein the first biasing voltage [increases over time] is negative relative to the anode; and

applying a plating voltage to the substrate once the substrate has been immersed into the electrolyte solution, the plating voltage being higher than the initial portion of the first biasing voltage. — p15, l23-24

86. (Amended) The method of claim 85, wherein the first biasing voltage [is] provides a ramping [voltage] current. pg 12, l28-30 p16, l9,10

87. (Amended) The method of claim 85, wherein the first biasing voltage [increases from about zero volt to a range of about 1 volt to about 5 volts] is about 0.8 volt. pg 12, line 1, 28

88. The method of claim 85, wherein the first biasing voltage is configured to limit etching by the electrolyte solution of a seed layer disposed on the one or more features formed on the substrate.

89. (Amended) The method of claim [85] 94, wherein the first biasing voltage and the second biasing voltage [is] are applied for about [0.125] 0.25 second to about [1 second] 5 seconds. pg 16, l11-12

90. (Amended) The method of claim 85, wherein the first biasing voltage [increases from about zero volt to a range of] ranges from about 1 volt to about 5 volts [in a period of about 0.125 second to about 1 second]. pg 15, line 24